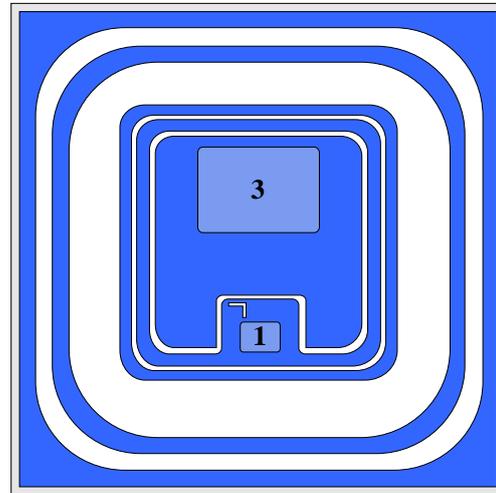


**3VD212800YL HIGH VOLTAGE MOSFET CHIPS**
**DESCRIPTION**

- ∅ 3VD212800YL is a High voltage N-Channel enhancement mode power MOS-FET chip fabricated in advanced silicon epitaxial planar technology.
- ∅ Advanced termination scheme to provide enhanced voltage-blocking capability.
- ∅ Avalanche Energy Specified
- ∅ Source-to-Drain Diode Recovery Time Comparable to a Discrete Fast Recovery Diode
- ∅ The chips may packaged in TO-220 type and the typical equivalent product is 1N80.
- ∅ The packaged product is widely used in AC-DC power suppliers, DC-DC converters and H-bridge PWM motor drivers.
- ∅ Die size: 2.12mm\*2.02mm.
- ∅ Chip Thickness: 300±20µm.
- ∅ Top metal : Al, Backside Metal : Ag.



PAD1:GATE      PAD3:SOURCE  
 CHIP TOPOGRAPHY

**ABSOLUTE MAXIMUM RATINGS (T<sub>amb</sub>=25°C)**

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V <sub>DS</sub>	800	V
Gate-Source Voltage	V <sub>GS</sub>	±30	V
Drain Current	I <sub>D</sub>	1.0	A
Power Dissipation (TO-220 Package)	P <sub>D</sub>	45	W
Operation Junction Temperature	T <sub>J</sub>	-55~+150	°C
Storage Temperature	T <sub>stg</sub>	-55~+150	°C

**ELECTRICAL CHARACTERISTICS (T<sub>amb</sub>=25°C)**

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Drain -Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250µA	800	-	-	V
Gate Threshold Voltage	V <sub>TH</sub>	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> =250µA	3	-	4.5	V
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =800V, V <sub>GS</sub> =0V	-	-	1	µA
Static Drain- Source On State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =0.5A	-	-	16	Ω
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±10	µA
Source-Drain Diode Forward on Voltage	V <sub>FSD</sub>	I <sub>S</sub> =1A, V <sub>GS</sub> =0V	-	-	1.6	V